

**FEATURES**

- 10 $\mu$ s Short Circuit Withstand
- Non Punch Through Silicon
- Isolated Cu Base with Al<sub>2</sub>O<sub>3</sub> Substrates
- Lead Free Construction

**APPLICATIONS**

- High Reliability Inverters
- Motor Controllers

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 600V to 3300V and currents up to 2400A.

The DIM400DDS12-A000 is a dual switch 1200V, n-channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) plus 10 $\mu$ s short circuit withstand. This device is optimised for traction drives and other applications requiring high thermal cycling capability.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

**ORDERING INFORMATION**

Order As:

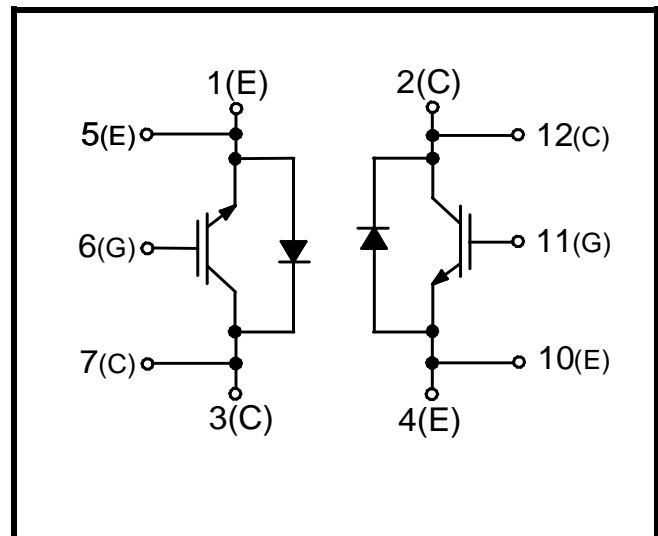
**DIM400DDS12-A000**

Note: When ordering, please use the complete part number

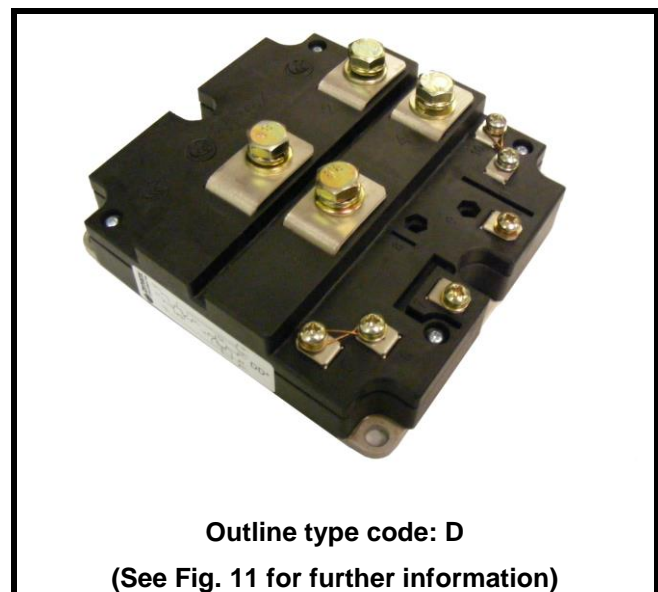
**KEY PARAMETERS**

$V_{CES}$	<b>1200V</b>
$V_{CE(sat)}$ * (typ)	<b>2.2 V</b>
$I_C$ (max)	<b>400A</b>
$I_{C(PK)}$ (max)	<b>800A</b>

\* Measured at the power busbars, not the auxiliary terminals



**Fig. 1 Circuit configuration**



Outline type code: D

(See Fig. 11 for further information)

**Fig. 2 Package**

**ABSOLUTE MAXIMUM RATINGS**

Stresses above those listed under ‘Absolute Maximum Ratings’ may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

**T<sub>case</sub> = 25°C unless stated otherwise**

Symbol	Parameter	Test Conditions	Max.	Units
V <sub>CES</sub>	Collector-emitter voltage	V <sub>GE</sub> = 0V	1200	V
V <sub>GES</sub>	Gate-emitter voltage		±20	V
I <sub>C</sub>	Continuous collector current	T <sub>case</sub> = 85°C	400	A
I <sub>C(PK)</sub>	Peak collector current	1ms, T <sub>case</sub> = 115°C	800	A
P <sub>max</sub>	Max. transistor power dissipation	T <sub>case</sub> = 25°C, T <sub>j</sub> = 150°C	3470	W
I <sup>2</sup> t	Diode I <sup>2</sup> t value	V <sub>R</sub> = 0, t <sub>p</sub> = 10ms, T <sub>j</sub> = 125°C	25	kA <sup>2</sup> s
V <sub>isol</sub>	Isolation voltage – per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	2500	V

**THERMAL AND MECHANICAL RATINGS**

Internal insulation material:	Al <sub>2</sub> O <sub>3</sub>
Baseplate material:	Cu
Creepage distance:	20mm
Clearance:	10mm
CTI (Comparative Tracking Index):	>600

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
R <sub>th(j-c)</sub>	Thermal resistance – transistor (per switch)	Continuous dissipation - junction to case	-	-	36	°C/kW
R <sub>th(j-c)</sub>	Thermal resistance – diode (per switch)	Continuous dissipation - junction to case	-	-	80	°C/kW
R <sub>th(c-h)</sub>	Thermal resistance – case to heatsink (per module)	Mounting torque 5Nm (with mounting grease)	-	-	8	°C/kW
T <sub>j</sub>	Junction temperature	Transistor	-	-	150	°C
		Diode	-	-	125	°C
T <sub>stg</sub>	Storage temperature range	-	-40	-	125	°C
	Screw torque	Mounting – M6	-	-	5	Nm
		Electrical connections – M4	-	-	2	Nm
		Electrical connections – M8	-	-	10	Nm

**ELECTRICAL CHARACTERISTICS**

**T<sub>case</sub> = 25°C unless stated otherwise.**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I <sub>CES</sub>	Collector cut-off current	V <sub>GE</sub> = 0V, V <sub>CE</sub> = V <sub>CES</sub>			0.5	mA
		V <sub>GE</sub> = 0V, V <sub>CE</sub> = V <sub>CES</sub> , T <sub>case</sub> = 125°C			12	mA
I <sub>GES</sub>	Gate leakage current	V <sub>GE</sub> = ± 20V, V <sub>CE</sub> = 0V			2	µA
V <sub>GE(TH)</sub>	Gate threshold voltage	I <sub>C</sub> = 20mA, V <sub>GE</sub> = V <sub>CE</sub>	4.5	5.5	6.5	V
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	V <sub>GE</sub> = 15V, I <sub>C</sub> = 400A		2.2	2.8	V
		V <sub>GE</sub> = 15V, I <sub>C</sub> = 400A, T <sub>j</sub> = 125°C		2.6	3.2	V
I <sub>F</sub>	Diode forward current	DC			400	A
I <sub>FM</sub>	Diode maximum forward current	t <sub>p</sub> = 1ms			800	A
V <sub>F</sub>	Diode forward voltage	I <sub>F</sub> = 400A		2.1	2.4	V
		I <sub>F</sub> = 400A, T <sub>j</sub> = 125°C		2.1	2.4	V
C <sub>ies</sub>	Input capacitance	V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V, f = 1MHz		45		nF
Q <sub>g</sub>	Gate charge	±15V		4		µC
C <sub>res</sub>	Reverse transfer capacitance	V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V, f = 1MHz				nF
L <sub>M</sub>	Module inductance – per switch			20		nH
R <sub>INT</sub>	Internal transistor resistance – per switch			270		µΩ
SC <sub>Data</sub>	Short circuit current, I <sub>SC</sub>	T <sub>j</sub> = 125°C, V <sub>CC</sub> = 900V t <sub>p</sub> ≤ 10µs, V <sub>GE</sub> ≤ 15V V <sub>CE(max)</sub> = V <sub>CES</sub> - L* x di/dt IEC 60747-9		2250		A

**Note:**

\* L is the circuit inductance + L<sub>M</sub>

**ELECTRICAL CHARACTERISTICS**

**T<sub>case</sub> = 25°C unless stated otherwise**

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
t <sub>d(off)</sub>	Turn-off delay time	I <sub>C</sub> = 400A V <sub>GE</sub> = ±15V V <sub>CE</sub> = 600V R <sub>G(ON)</sub> = 3.3Ω R <sub>G(OFF)</sub> = 3.3Ω L <sub>S</sub> ~ 100nH		710		ns
t <sub>f</sub>	Fall time			70		ns
E <sub>OFF</sub>	Turn-off energy loss			60		mJ
t <sub>d(on)</sub>	Turn-on delay time			190		ns
t <sub>r</sub>	Rise time			100		ns
E <sub>ON</sub>	Turn-on energy loss			40		mJ
Q <sub>rr</sub>	Diode reverse recovery charge		I <sub>F</sub> = 400A V <sub>CE</sub> = 600V di <sub>F</sub> /dt = 4700A/μs		55	
I <sub>rr</sub>	Diode reverse recovery current			300		A
E <sub>rec</sub>	Diode reverse recovery energy			17		mJ

**T<sub>case</sub> = 125°C unless stated otherwise**

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
t <sub>d(off)</sub>	Turn-off delay time	I <sub>C</sub> = 400A V <sub>GE</sub> = ±15V V <sub>CE</sub> = 600V R <sub>G(ON)</sub> = 3.3Ω R <sub>G(OFF)</sub> = 3.3Ω L <sub>S</sub> ~ 100nH		890		ns
t <sub>f</sub>	Fall time			100		ns
E <sub>OFF</sub>	Turn-off energy loss			60		mJ
t <sub>d(on)</sub>	Turn-on delay time			440		ns
t <sub>r</sub>	Rise time			125		ns
E <sub>ON</sub>	Turn-on energy loss			60		mJ
Q <sub>rr</sub>	Diode reverse recovery charge		I <sub>F</sub> = 400A V <sub>CE</sub> = 600V di <sub>F</sub> /dt = 4000A/μs		85	
I <sub>rr</sub>	Diode reverse recovery current			320		A
E <sub>rec</sub>	Diode reverse recovery energy			32		mJ

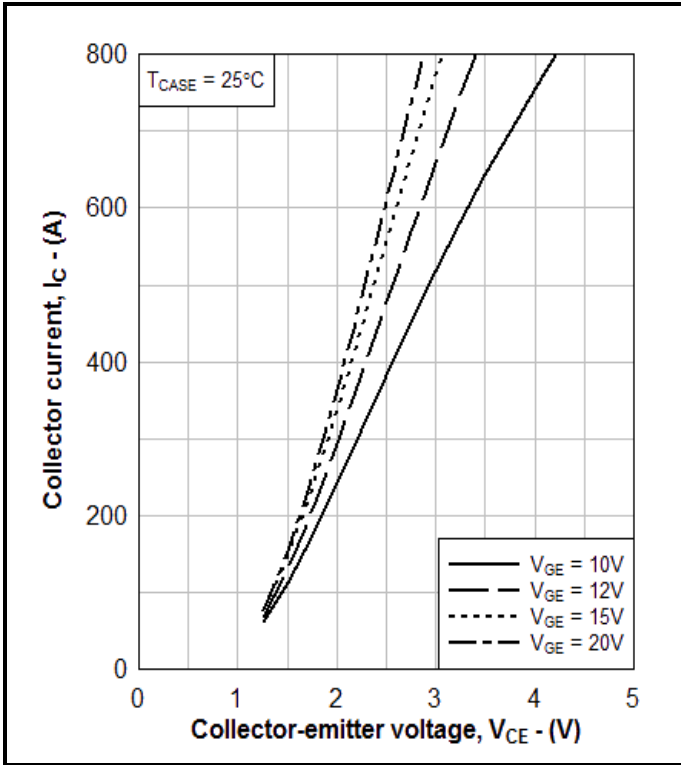


Fig. 3 Typical output characteristics

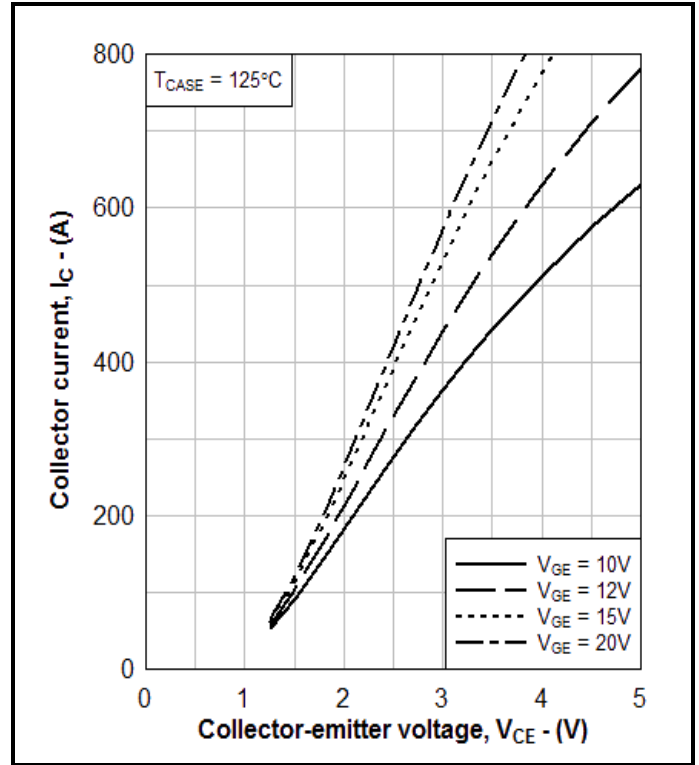


Fig. 4 Typical output characteristics

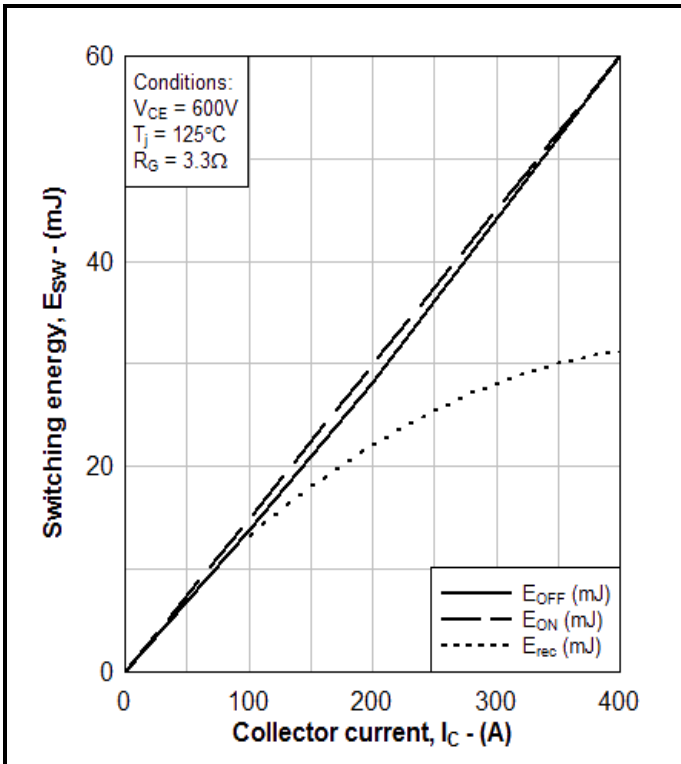


Fig. 5 Typical switching energy vs collector current

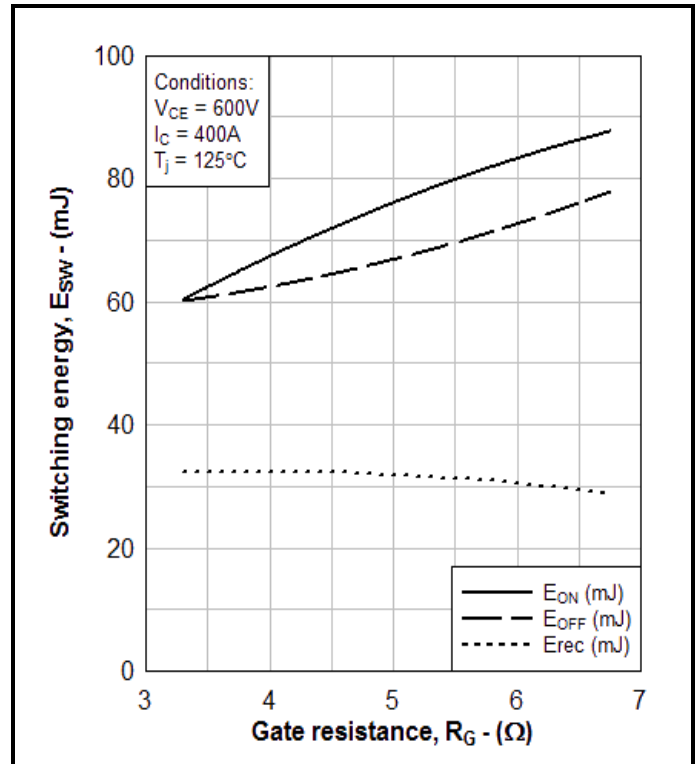


Fig. 6 Typical switching energy vs gate resistance

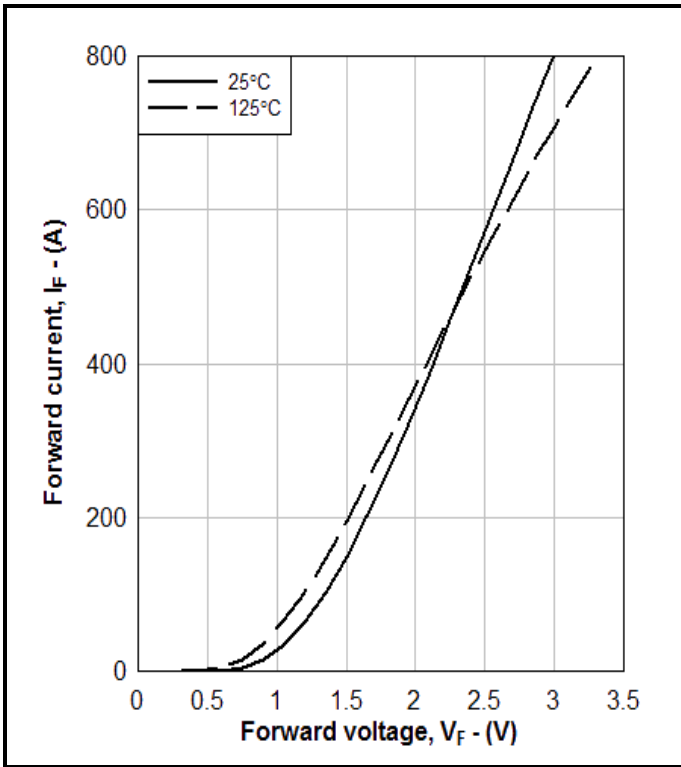


Fig. 7 Diode typical forward characteristics

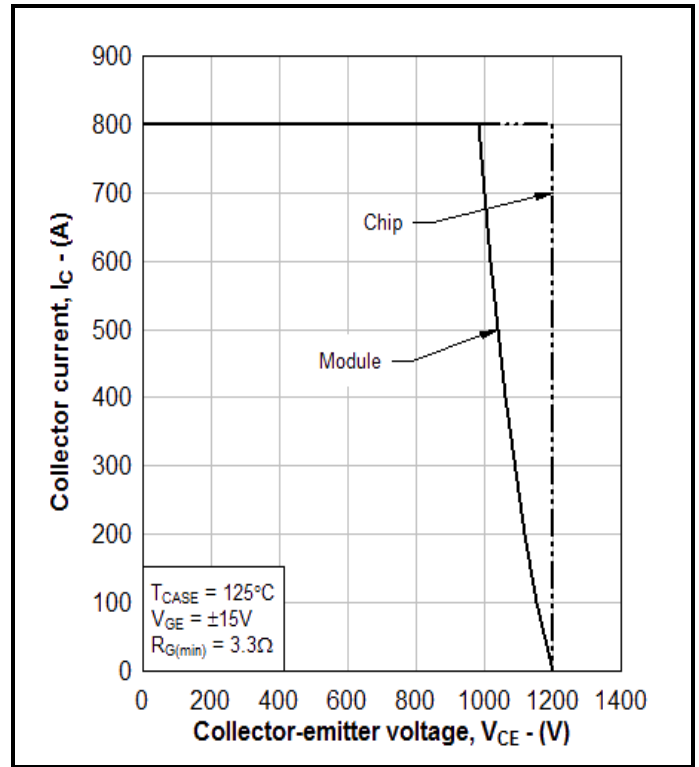


Fig. 8 Reverse bias safe operating area

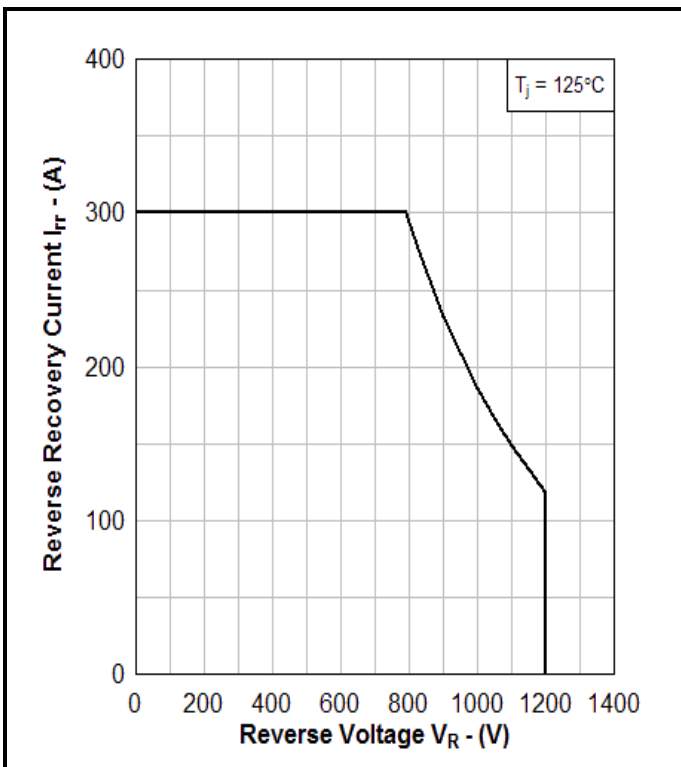


Fig. 9 Diode reverse bias safe operating area

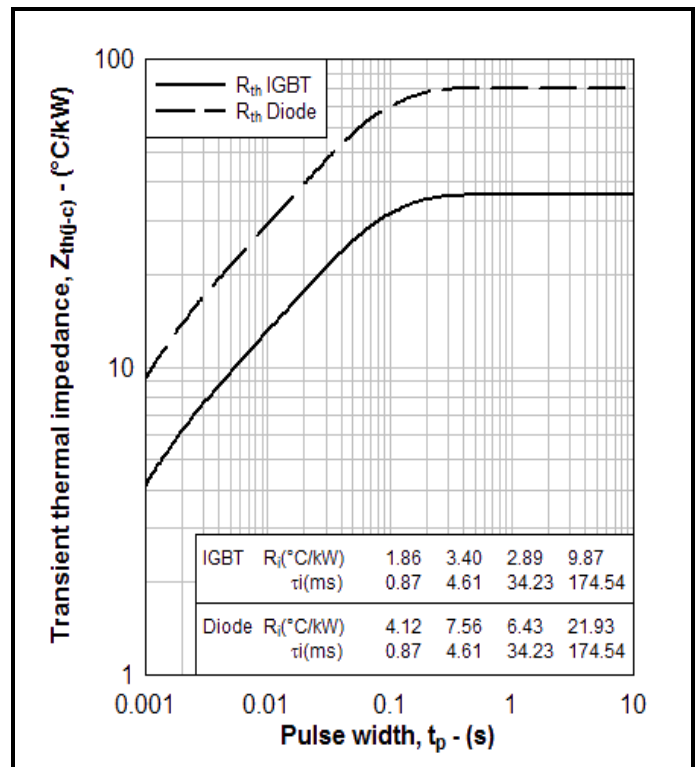
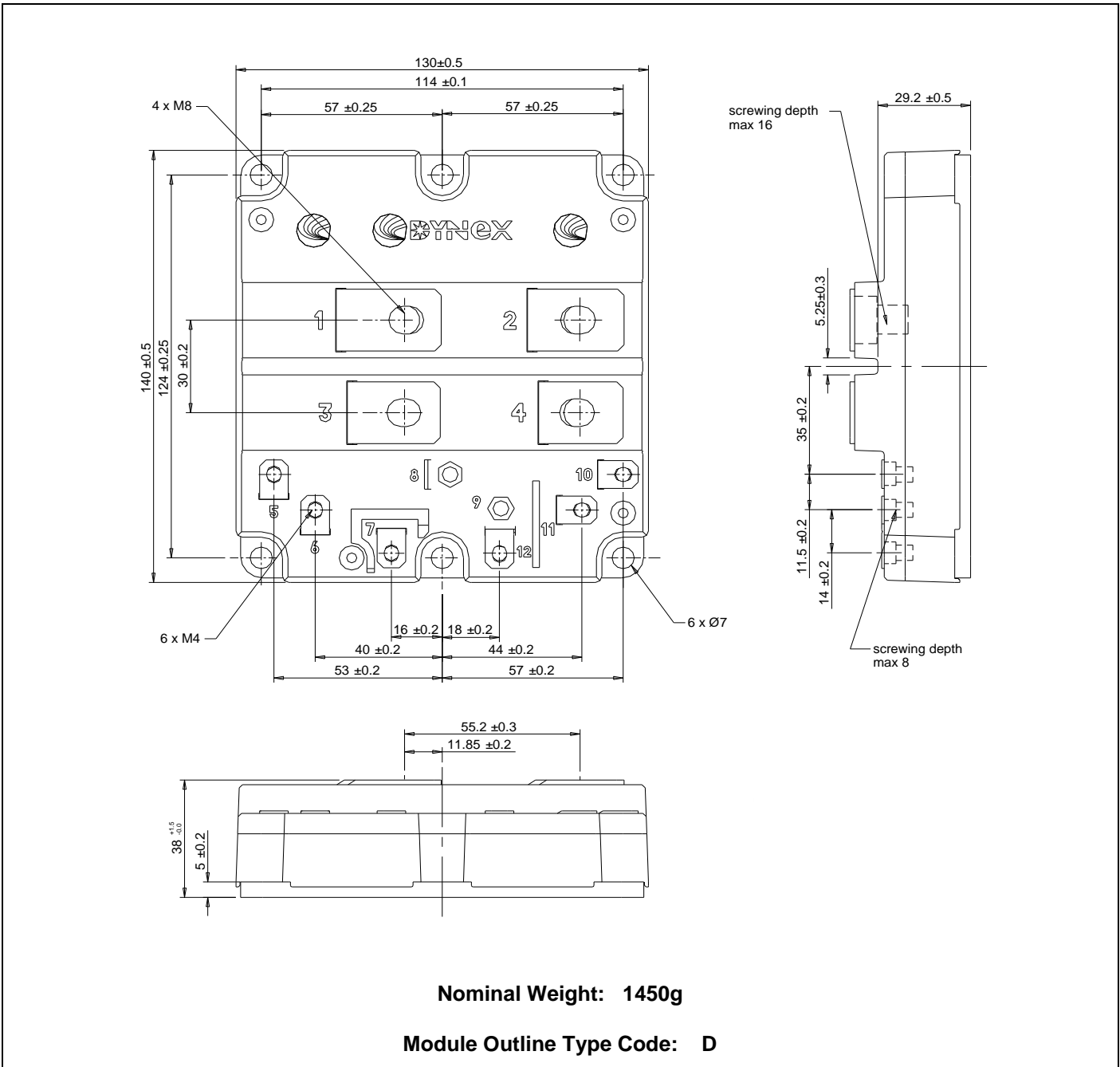


Fig. 10 Transient thermal impedance

**PACKAGE DETAILS**

For further package information, please visit our website or contact Customer Services.  
 All dimensions in mm, unless stated otherwise.  
**DO NOT SCALE.**



**Nominal Weight: 1450g**

**Module Outline Type Code: D**

**Fig. 11 Module outline drawing**

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